

the second solder alloy contains 3 - 4 mass % of Ag.

11. (previously presented) A solder paste as claimed in claim 8 wherein:

at least one of the first and second solder alloys contains Bi;

the first solder alloy is selected from a Sn-Ag-In alloy and a Sn-Ag-In-Bi alloy; and

the second solder alloy is selected from a Sn-Ag alloy, a Sn-Ag-Bi alloy, a Sn-Ag-Cu alloy, and a Sn-Ag-Bi-Cu alloy.

12. (previously presented) A solder paste as claimed in claim 11 wherein:

the first solder alloy contains 3 - 4 mass % of Ag and 6 - 20 mass % of In; and

the second solder alloy contains 3 - 4 mass % of Ag.

13. (previously presented) A solder paste as claimed in claim 8 wherein:

the first solder alloy is selected from a Sn-Ag-In alloy and a Sn-Ag-In-Bi alloy; and

the second solder alloy is selected from a Sn-Ag-Cu alloy and a Sn-Ag-Bi-Cu alloy.

14. (previously presented) A solder paste as claimed in claim 13 wherein:

the first solder alloy contains 3 - 4 mass % of Ag and 6 -

20 mass % of In; and

the second solder alloy contains 3 - 4 mass % of Ag.

15. (previously presented) A solder paste as claimed in claim 8 wherein the first solder alloy has a lower main peak temperature measured by differential thermal analysis than the second solder alloy.

16. (new) A solder paste as claimed in claim 8 wherein the overall composition after melting of the first and second solder alloy powders contains 6 - 10 mass % of In.